

# **Product and Process Change Notice**

PCN No.	PCN03054	PCN Date	10/18/2022	Effective Date	10/18/2022
Title	Qualification of ChipMos as an additional Assembly Site for 48 ball BGA Package				

#### Type: Minor

Everspin is adding ChipMos as an additional Assembly Site for 48 ball BGA Package.

#### **Reason For Change**

Improved manufacturing efficiency and capacity at assembly site.

#### **Affected Products**

Part Number	Description
MR4A08BCMA35	Industrial Temp
MR4A08BMA35	Commercial Temp
MR4A08BCMA35R	Industrial Temp, T&R
MR4A08BMA35R	Commercial Temp, T&R

#### Impact on Form, Fit, Function, Quality or Reliability

No Impact

# **Proposed First Ship Date for Change:**

November 18, 2022

# **Key Material Differences**

Material	Old- UDG	New - CHM
Die Attach (S203)	Henkel QMI-536NB (epoxy)	Henkel QMI-550 (Epoxy)
Die Attach (B102)	QMI536NB	Nitto EM-760 (DAF)
Die Attach (S101)	Henkel QMI-536NB (epoxy)	Henkel 2025D (Epoxy)
Mold Compound	GE100-AT	Sumitomo G760LB
Wire Bond	Au 4N 1.3mil	Tanaka Au 2N 0.7mil
Substrate	HL-832NXA(Mitsubishi)	ZDT 832NXA+ AUS308

#### **Product Identifier**

Assembly site code = H for ChipMos Taiwan

# **Supplier Qual Plan Schedule and Results**

Site package qualification is complete and all Everspin requirements met. QUA03055 QR

# **Date Qualification Samples Are Available:**

Samples are generally available now but please request your specific part number to your Everspin Sales contact.

# **Acceptance of Change**

Everspin will consider this change accepted unless specific conditions for acceptance are provided in writing within 30 days of receipt of this notice.



# Product and Process Change Notice

PCN No.	PCN03054	PCN Date	10/12/2022	Effective Date	10/10/2022
Title	Qualification of ChipMos as an additional Assembly Site for 48 ball BGA Package				

Contact Information		Sample Information Sample	es Available Now		
Everspin Quality Everspin Technologies (480) 347-1084 bonnie.paro@everspin.com		Contact Everspin sales: <a href="http://www.everspin.com/contact-us-everspin-technologies">http://www.everspin.com/contact-us-everspin-technologies</a> If using the on-line sample request, please refer to this PCN # to receive samples.			
Originator					
<u>Date</u> 10/17/2022 <u>Title</u> Senior		r Quality Engineer	Name Bonnie S. Paro Boni S. Laco		
Approval and Release					
<u>Date</u> 10/17/2022	<u>Title</u> VP of	Fab Ops & Quality	Name Khaldoun Barakat Mallam Ambat		
<u>Date</u> 10/17/2022	<u>Title</u> VP of	Backend Operations	Name Amit Shah		
<u>Date</u> 10/13/2022	<u>Title</u> Sr. Dir	ector of Marketing	Name Joe O'Hare		